

# LNPT<sup>™</sup> LUBRICOMP<sup>™</sup> COMPOUND DCL33E

DCL4033

## DESCRIPTION

LNP LUBRICOMP DCL33E compound is based on Polycarbonate (PC) resin containing 15% carbon fiber and 15% PTFE. Added features of this grade include: Wear Resistant, Electrically Conductive, Easy Molding.

GENERAL INFORMATION	
Features	Electrically Conductive, Good Processability, Wear resistant, High stiffness/Strength
Fillers	Carbon Fiber, PTFE
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, break, 5 mm/min	121	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.8	%	ISO 527
Flexural Stress, break, 2 mm/min	177	MPa	ISO 178
Flexural Modulus, 2 mm/min	11900	MPa	ISO 178
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched 80*10*4 +23°C	25	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m <sup>2</sup>	ISO 180/1A
<b>THERMAL <sup>(1)</sup></b>			
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	139	°C	ISO 75/Af
Relative Temp Index, Elec <sup>(2)</sup>	80	°C	UL 746B
Relative Temp Index, Mech w/impact <sup>(2)</sup>	80	°C	UL 746B
Relative Temp Index, Mech w/o impact <sup>(2)</sup>	80	°C	UL 746B
<b>PHYSICAL <sup>(1)</sup></b>			
Mold Shrinkage, flow <sup>(3)</sup>	0.15 – 0.3	%	SABIC method
Density	1.35	g/cm <sup>3</sup>	ISO 1183
<b>ELECTRICAL <sup>(1)</sup></b>			
Surface Resistivity	1.E+02 – 1.E+04	Ω	ASTM D257
<b>FLAME CHARACTERISTICS <sup>(2)</sup></b>			
UL Yellow Card Link	<a href="#">E45329-101343782</a>	-	-

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
UL Recognized, 94V-0 Flame Class Rating	≥4.5	mm	UL 94
UL Recognized, 94HB Flame Class Rating	≥0.8	mm	UL 94
<b>INJECTION MOLDING <sup>(4)</sup></b>			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	305 – 325	°C	
Front - Zone 3 Temperature	320 – 330	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	295 – 305	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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